



PNC's Technology Roadmap

PNC's technology road map is a guide to enable us to schedule planned improvement in our current capabilities to serve our customer better. It also helps us to fulfill our commitment to ISO9001:2008 requirement of continuous improvement to achieve measurable customer satisfaction.

Following table shows our current capability as of Sept 29th, 2011 and also our plan for years 2012 and 2013.

No.	Manufacturing Capabilities	2011	2012	2013
1	Drilling Aspect Ratio	6:1	9:1	15:1
2	Minimum Drill Size	.006	.005	.004
3	Minimum Inner Layer Pad Size	.018	.016	.014
4	Minimum Outer Layer Pad Size	.018	.016	.014
5	Minimum Anti-Pad on Power/Ground Planes	.018	.016	.014
6	Minimum Buried/Blind Via Pad Size	.018	.016	.014
7	Minimum Buried/Blind Via Hole Size	.010	.008	.006
8	Minimum Inner Layer Line Width	.003	.003	.003
9	Minimum Outer Layer Line Width	.003	.003	.003
10	Minimum Inner Layer Spacing	.003	.003	.003
11	Minimum Outer Layer Spacing	.003	.003	.003
12	Maximum Overall Board Thickness	.250	.250	.250
13	Minimum Dielectric Thickness	.003	.0025	.002
14	Minimum Component Pitch-Plating and Testing	.012	.010	.008
15	Layer to Layer Registration Tolerance	.004	.004	.003
16	Conductor to Board Edge	.010	.008	.005
17	Solder Mask Clearance	.004	.003	.002
18	Solder Mask Dam between SMT Pads	.003	.003	.002
19	Minimum Base Copper Weight in oz.	.5	.5	.25
20	Maximum Overall Copper thickness	5	6	8
21	Maximum Layer Count	18	24	30
22	Plated Hole Tolerance	±.003	±.002	±.002
23	Maximum PCB Dimensions	19x25	19x25	19x25
24	Impedance Tolerance	±8%	±7.5%	±5%
26	Equipments Purchase Plan	Laser Drill – Year 1Q, 2012 Direct Imaging – Year 2Q, 2012 Plasma Etch System - Year 3Q,2012 Horizontal Black Oxide- Year 2Q, 2012 Primary Developer Year 1Q, 2012		